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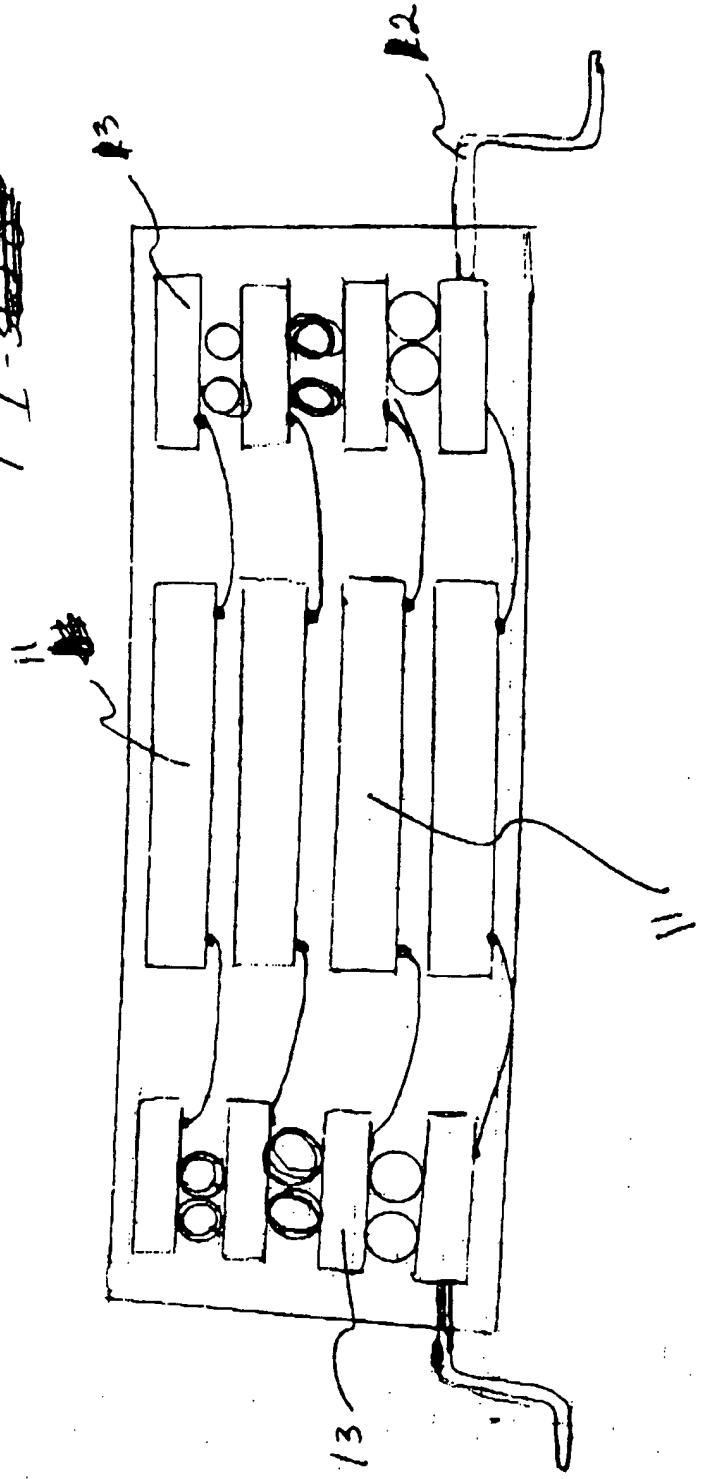
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FIGURE 1 (Prior Art)

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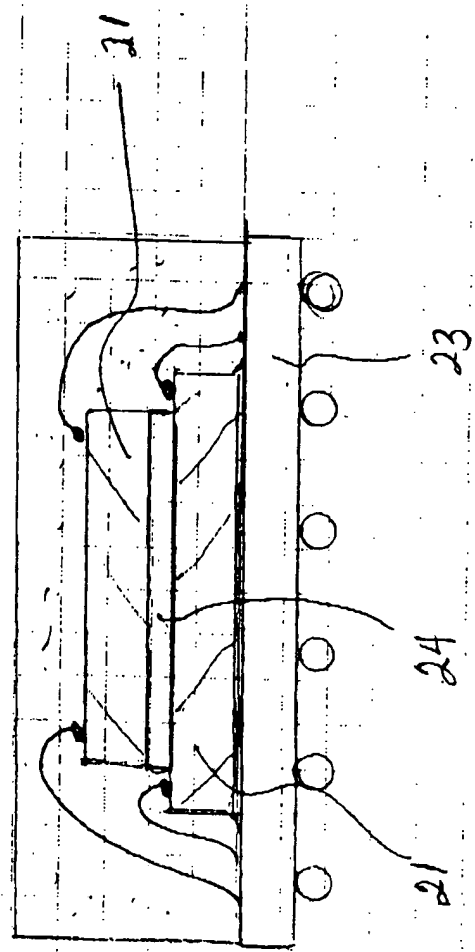


FIGURE 2

(PRIOR ART)

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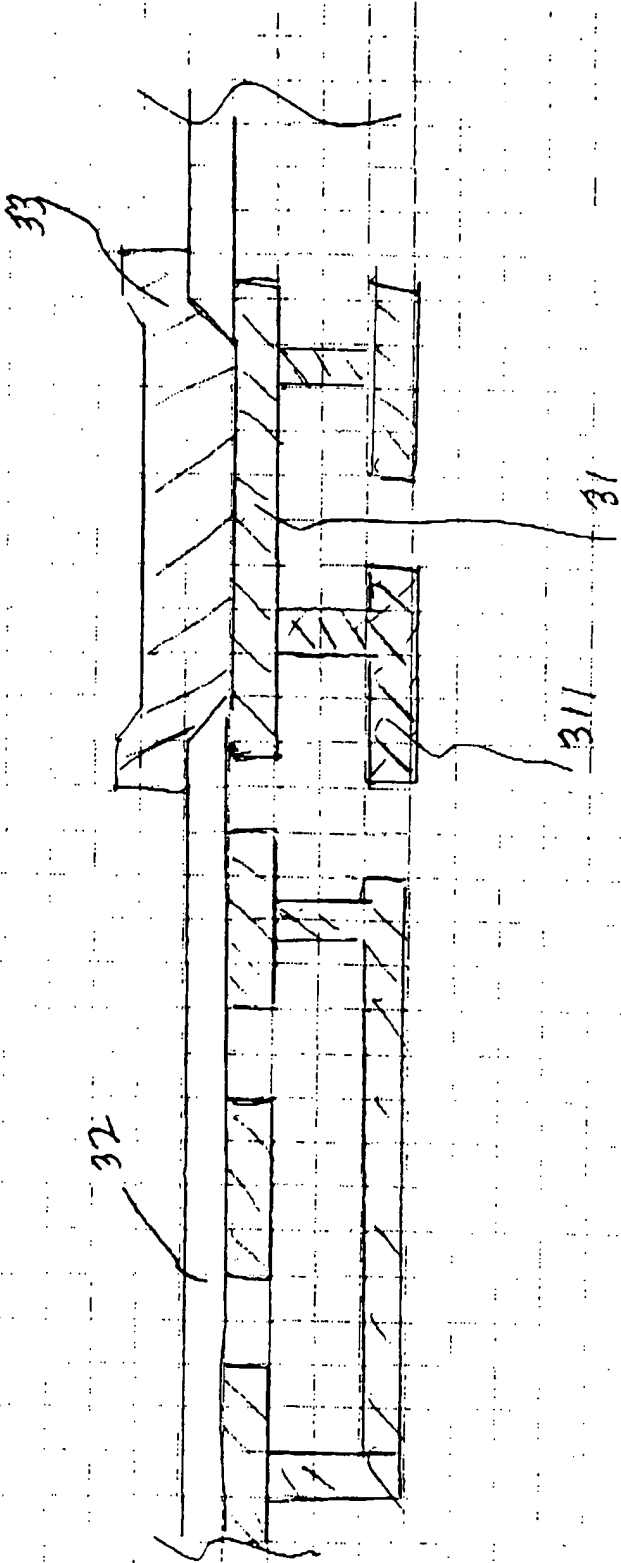


FIGURE 3

(PRIOR ART)

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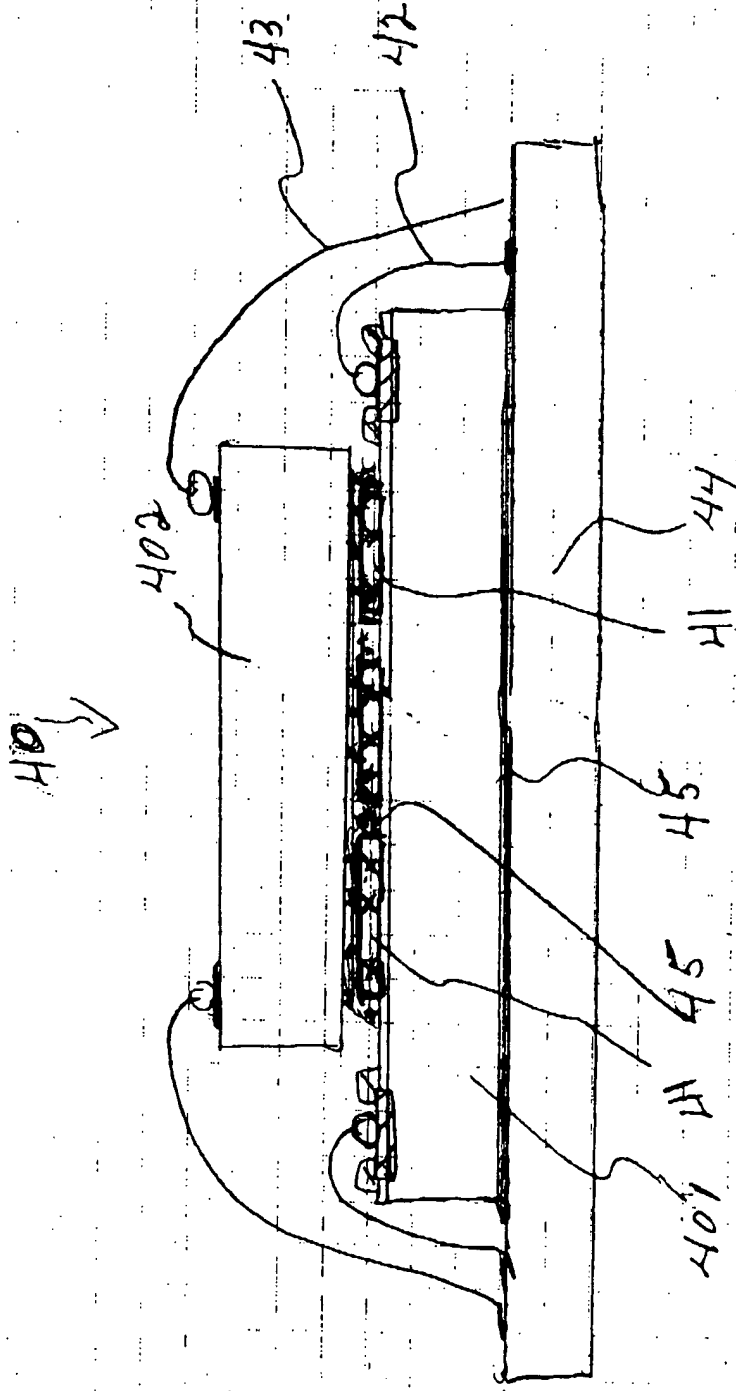


FIGURE 4

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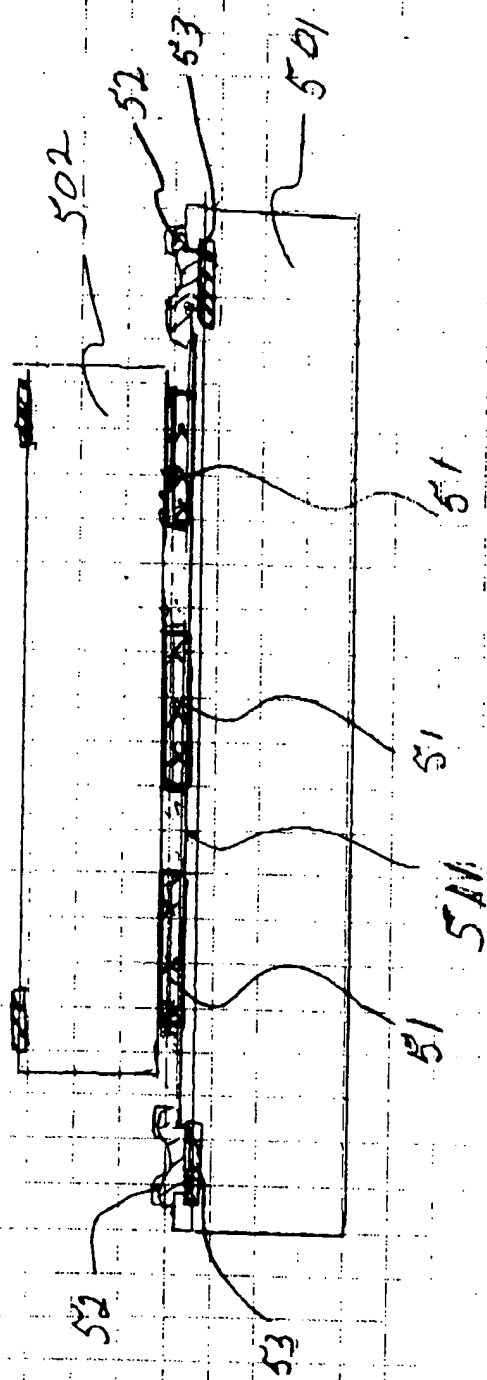


FIGURE 5a

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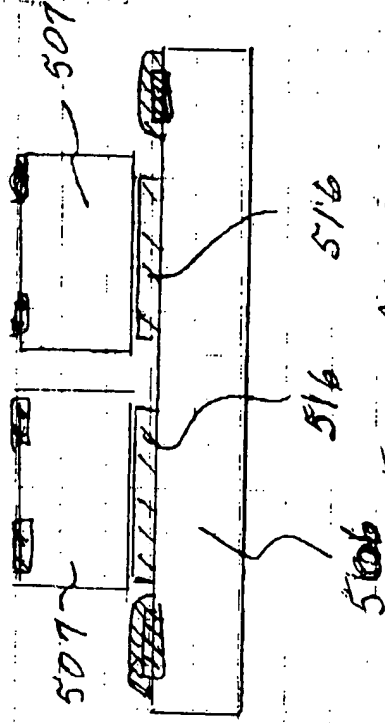
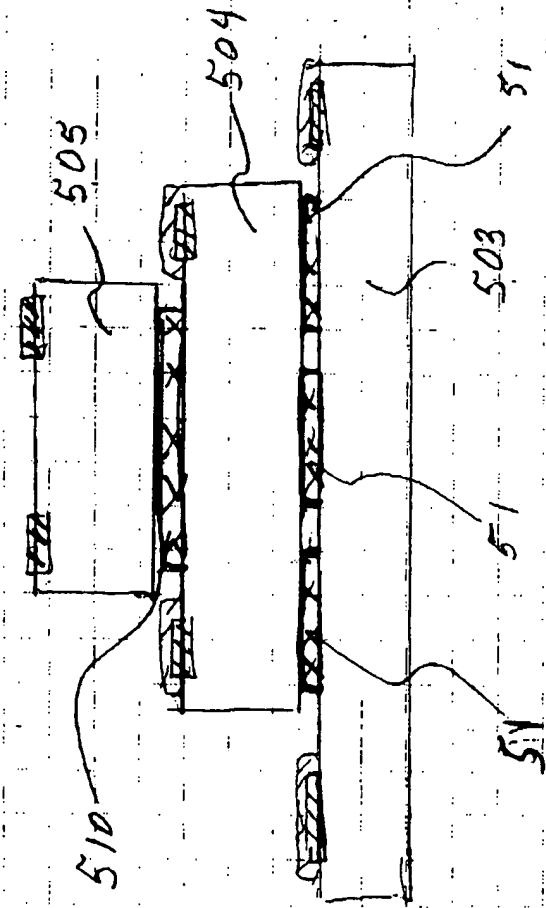


FIGURE 5c

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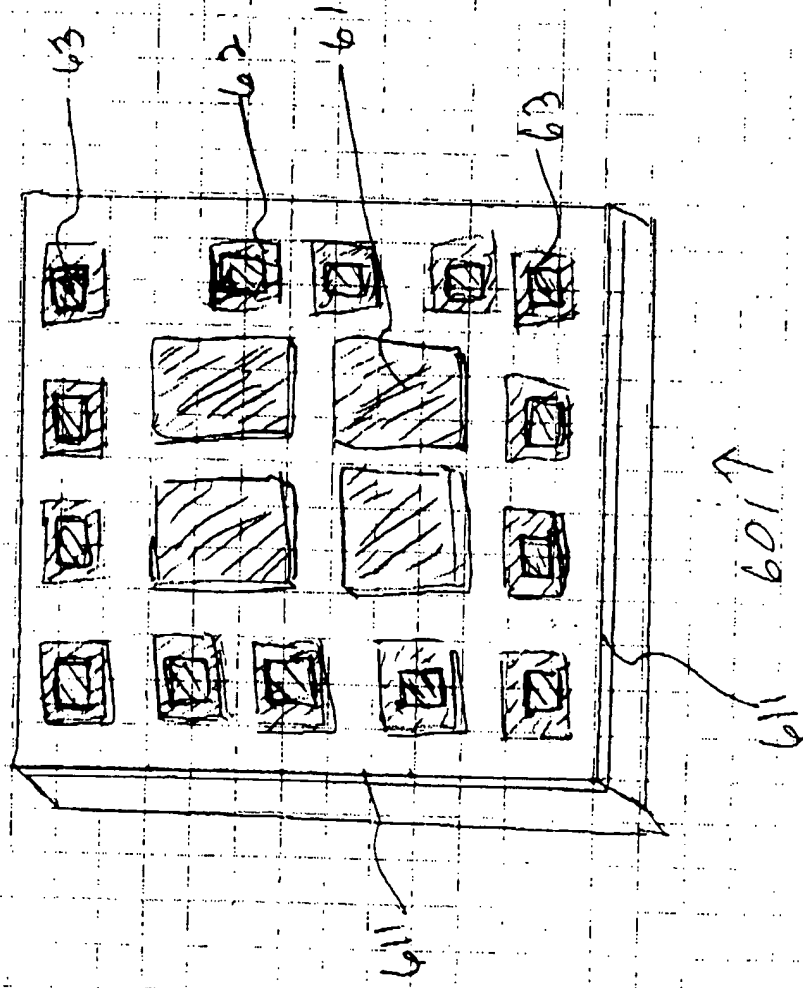
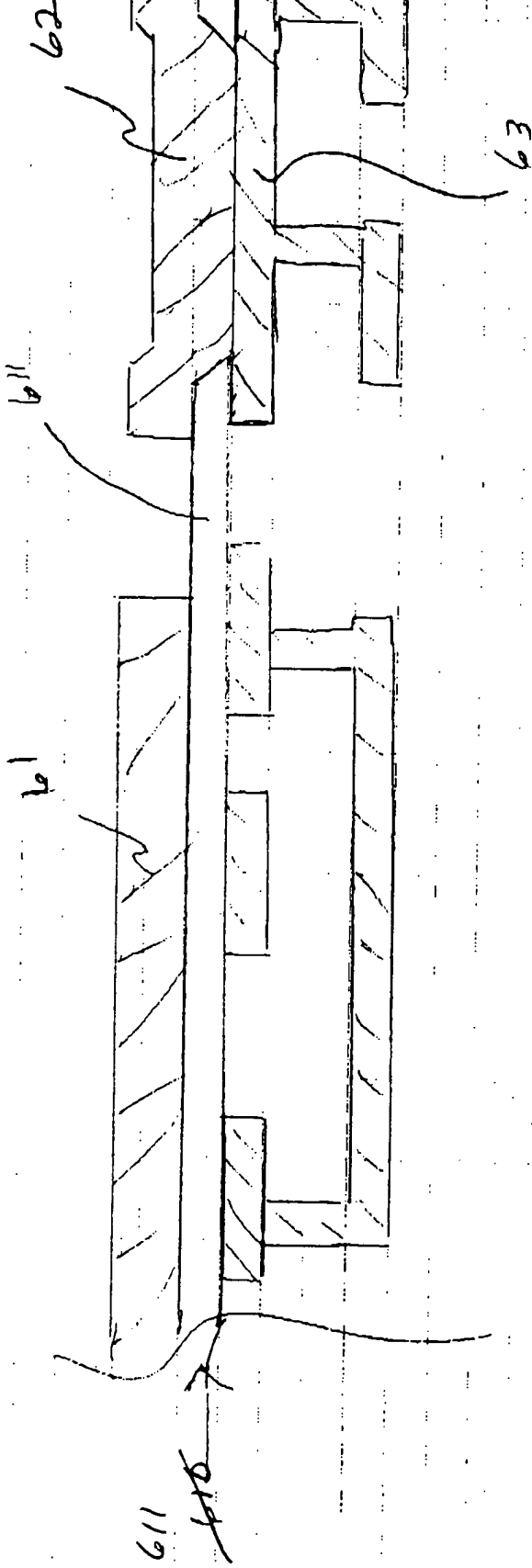


FIGURE 1a



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FIGURE 6b

Figure 7

Metal Island Standoff Process Flow

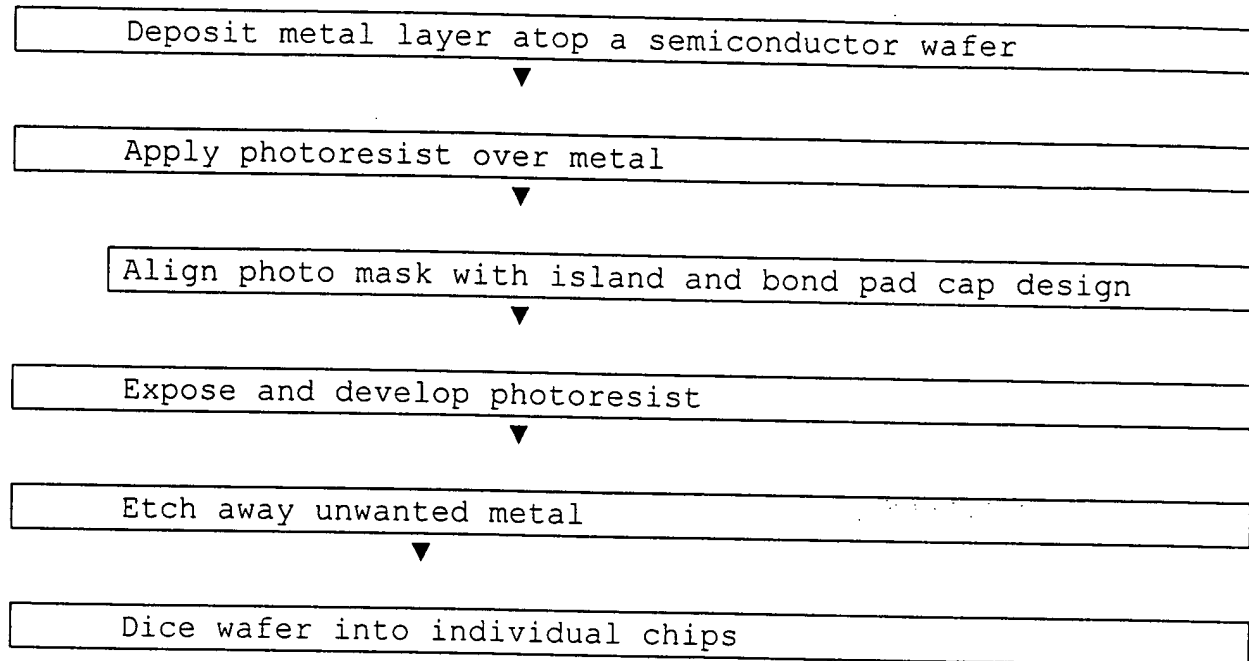


Figure 8

Stacked Chip Device Assembly Process

